

Title (en)
METAL CASING AND MANUFACTURING METHOD THEREOF

Title (de)
METALLGEHÄUSE UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
BOÎTIER MÉTALLIQUE ET SON PROCÉDÉ DE FABRICATION

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Application
EP 17870315 A 20170524

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Abstract (en)
The present invention discloses a metal enclosure and a metal enclosure manufacturing method. A thin metal layer is deposited in an electrical connection contact region on a housing of a metal enclosure, and abrasion resistance and corrosion resistance of the thin metal layer are better than those of a metal base material used for the housing. Therefore, in an actual using process, the thin metal layer is exposed on the electrical connection contact, and because of high abrasion resistance and high corrosion resistance of the thin metal layer, generation of particles in repeated rubbing between the electrical connection contact and a metal spring plate on a mainboard of an electronic device can be avoided, so as to avoid impact exerted on conductivity of the electrical connection contact by oxidation and accumulation of the particles. In the prior art, a metal slice is fastened to an electrical connection contact by means of laser welding, ultrasonic welding, screwing, or the like. By contrast, in embodiments of the present invention, deposition of the thin metal layer is not limited by cavity space of the housing, and may be implemented on an electrical connection contact of any area size. Therefore, in the embodiments of the present invention, a conduction problem of an electrical connection contact on a metal enclosure can be thoroughly resolved.

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